



Form PTO-1449 DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	ATTY. DKT. NO. 219.40606X00	SERIAL NO. 10/066,645
	APPLICANT Scot A. KELLAR et al.	
	FILING DATE February 6, 2002	GROUP 2811 2813

U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date
AA						
AB						
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AI						
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FOREIGN PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation	
						Yes	No
AM							
AN							
AO							
AP							
AQ							
AR							
AS							
AT							

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

NB	AU	"Ultra Thin Electronics for Space Applications", 2001 Electronic Components and Technology Conference, 2001 IEEE
NB	AV	"Copper Wafer Bonding"; A. Fan, A. Rahman, and R. Reif; Electrochemical and Solid-State Letters, 2 (10) 534-536 (1999)
NB	AW	"Face to Face Wafer Bonding for 3D Chip Stack Fabrication to Shorten Wire Lengths", June 27-29, 2000 VMIC Conference 2000 IMIC - 200/00/0090(c)
NB	AX	"InterChip Via Technology for Vertical System Integration", Fraunhofer Institute for Reliability and Microintegration, Munich, Germany; Infineon Technologies AG, Munich, Germany; 2001 IEEE
	AY	
	AZ	
Examiner Noma Berezny		Date Considered 6/4/03